

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE  
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2007

Complete if Known

Application Number	10/756,901
Filing Date	January 14, 2004
First Named Inventor	Farrar, Paul
Group Art Unit	2823
Examiner Name	Clark, Sheila

Sheet 1 of 1

Attorney Docket No: 303.572US2

**US PATENT DOCUMENTS**

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
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**FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T*

**OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
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EXAMINER

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2/19/01